

N and P Channel 30V MOSFET

GENERAL DESCRIPTION

The JY12M is the N and P Channel logic enhancement mode power field transistors are produced using high cell density DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits where high-side switching, and low in-line power loss are needed in a very small outline surface mount package.

FEATURES

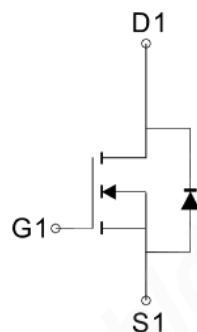
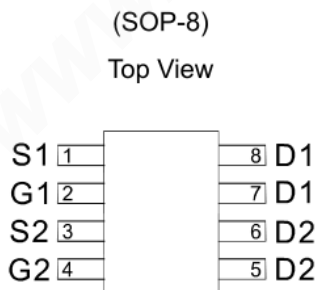
Device	$R_{DS(ON) \text{ MAX}}$	$I_{D \text{ MAX}}(25^{\circ} \text{ C})$
N-Channel	$20\text{m}\Omega @ V_{GS}=10\text{V}$	8.5A
	$32\text{m}\Omega @ V_{GS}=4.5\text{V}$	7.0A
P-Channel	$45\text{m}\Omega @ V_{GS}=-10\text{V}$	-5.5A
	$85\text{m}\Omega @ V_{GS}=-4.5\text{V}$	-4.1A

- Low Input Capacitance
- Fast Switching Speed

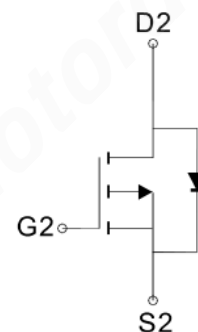
APPLICATIONS

- Power Management
- DC/DC Converter
- DC Motor Control
- LCD TV & Monitor Display Inverter
- CCFL inverter

PIN CONFIGURATION



N-Channel MOSFET



P-Channel MOSFET

Absolute Maximum Ratings($T_a=25^{\circ}\text{C}$ Unless Otherwise Noted)

Parameter		Symbol	N Channel		P Channel		Unit
			10 sec	Steady	10 sec	Steady	
Drain Source Voltage		V _{DSS}	30		-30		V
Gate Source Voltage		V _{DSS}	± 20		± 20		
Continuous	Ta=25 °C	I _D	8.5	6.5	-7.0	-5.3	A
Drain Current	Ta=70 °C		6.8	5.1	-5.5	-4.1	
Pulsed Drain Current		I _{DM}	30		-30		
Maximum Power	Ta=25 °C	P _D	1.5				W
Dissipation	Ta=70 °C		0.95				
Operating Junction Temperature		T _J	-55 to 150				°C
Thermal Resistance Junction to Ambient		R _{θJA}	61	100	62	103	°C/W
Thermal Resistance Junction to Case		R _{θJC}	15		15		°C/W

Electrical Characteristics($T_a=25^{\circ}\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static							
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	N-Ch	1.0	1.5	3.0	V
		V _{DS} =V _{GS} , I _D =-250uA	P-Ch	-1.0	-1.5	-3.0	
I _{GSS}	Gate Leakage Current	V _{DS} =0V, V _{GS} =±20V	N-Ch			±100	nA
			P-Ch			±100	
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =30V, V _{GS} =0V	N-Ch			1	uA
		V _{DS} =-30V, V _{GS} =0V	P-Ch			-1	
I _{D(ON)}	On-State Drain Current	V _{DS} ≥5V, V _{GS} =10V	N-Ch	20			A
		V _{DS} ≤-5V, V _{GS} =-10V	P-Ch	-20			
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =10V, I _D =7.4A	N-Ch		15	20	mΩ
		V _{GS} =-10V, I _D =-5.2A	P-Ch		38	45	
		V _{GS} =4.5V, I _D =6.0A	N-Ch		23	32	
		V _{GS} =-4.5V, I _D =-4.0A	P-Ch		65	85	
V _{SD}	Diode Forward Voltage	I _S =1.7A, V _{GS} =0V	N-Ch		0.8	1.2	V
		I _S =-1.7A, V _{GS} =0V	P-Ch		-0.8	-1.2	

Electrical Characteristics(Ta=25°C Unless Otherwise Noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
Dynamic							
Qg	Total Gate Charge	N-Channel V _{DS} =15V,V _{GS} =10V, I _D =10A P-Channel V _{DS} =-15V,V _{GS} = -10V,I _D =-6A	N-Ch		9.8	nC	
			P-Ch		10.5		
Qgs	Gate-Source Charge		N-Ch		1.6		
			P-Ch		1.8		
Qgd	Gate-Drain Charge		N-Ch		2.0		
			P-Ch		1.9		
Ciss	Input Capacitance	N-Channel V _{DS} =15V,V _{GS} =0V, f=1MHz P-Channel V _{DS} =-25V,V _{GS} =0V, f=1MHz	N-Ch		501	pF	
			P-Ch		590		
Coss	Output Capacitance		N-Ch		72		
			P-Ch		69		
Crss	Reverse Transfer Capacitance		N-Ch		57		
			P-Ch		53		
Rg	Gate Resistance	V _{DS} =0V,V _{GS} =0V, f=1MHz	N-Ch		1.84	Ω	
			P-Ch		11		
rrT _{d(on)}	Turn-On Delay Time	N-Channel V _{DD} =15V,V _{GS} =10V, R _G =6Ω,I _D =1A P-Channel V _{DD} =-15V,V _{GS} =-10 V, R _G =6Ω,I _D =-1A	N-Ch		3.9	ns	
			P-Ch		6.8		
T _r	Turn-On Rise Time		N-Ch		4.2		
			P-Ch		4.9		
T _{d(off)}	Turn-Off Delay Time		N-Ch		16.6		
			P-Ch		28.4		
T _f	Turn-Off Fall Time		N-Ch		5.5		
			P-Ch		12.4		
T _{rr}	Reverse Recovery Time	I _F =12A, di/dt=500A/us	N-Ch		5.5	ns	
			P-Ch		14		
Q _{rr}	Reverse Recovery Charge		N-Ch		2.6	nC	
			P-Ch		11		

*The device mounted on 1in2 FR4 board with 2oz copper.

*Guaranteed by design. Not subject to product testing.

Typical Characteristics($T_J=25^{\circ}\text{C}$ Noted)

N-Channel

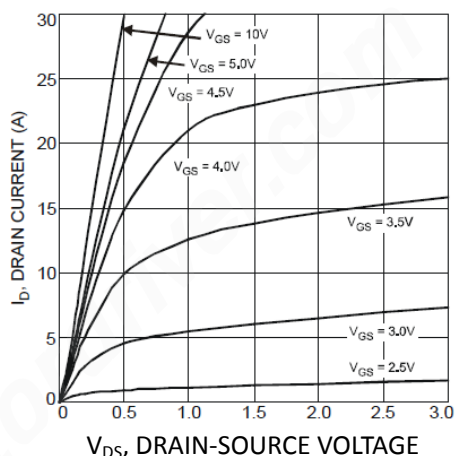


Figure1. Typical Output Characteristic

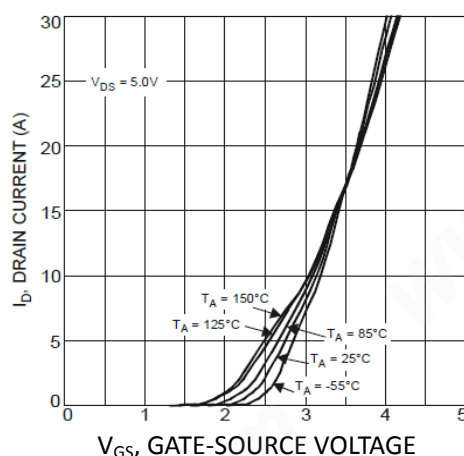


Figure2. Typical Transfer Characteristic

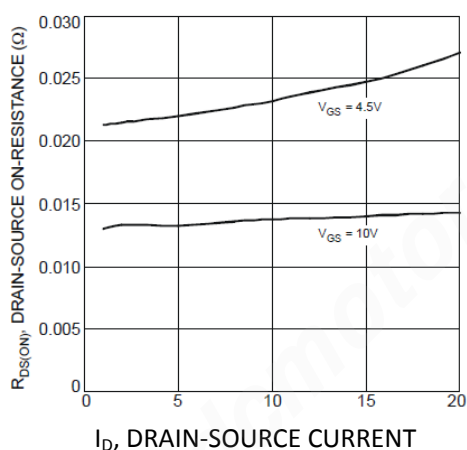


Figure3. Typical On-Resistance vs. Drain Current and Gate Voltage

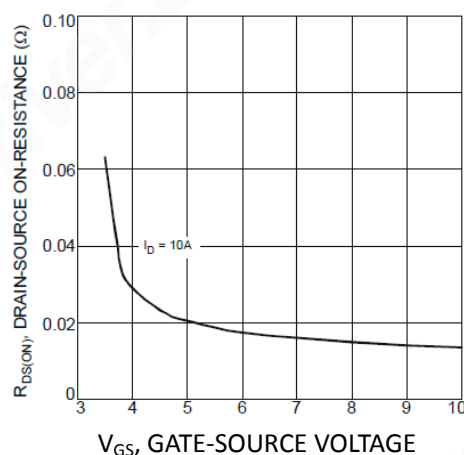


Figure4. Typical On-Resistance vs. Drain Current and Gate Voltage

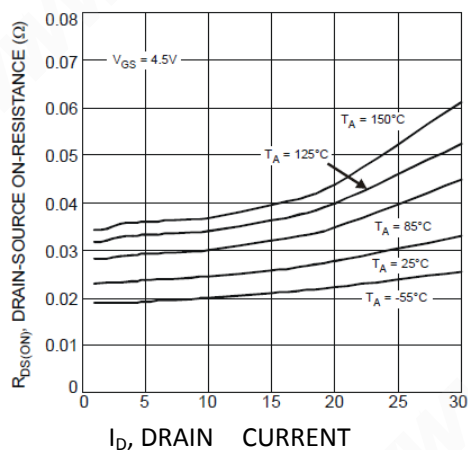


Figure5. Typical On-Resistance vs. Drain Current and Temperature

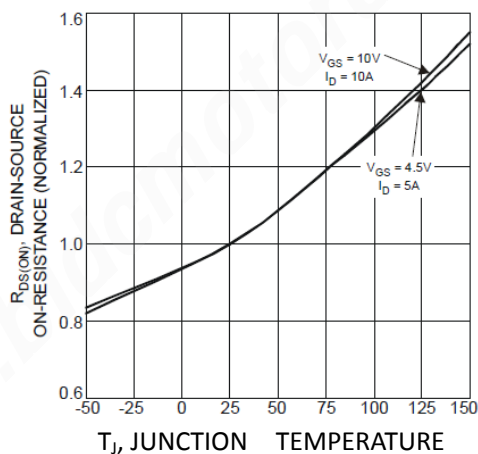


Figure6. On-Resistance Variation with Temperature

Typical Characteristics($T_J=25^{\circ}\text{C}$ Noted)

N-Channel

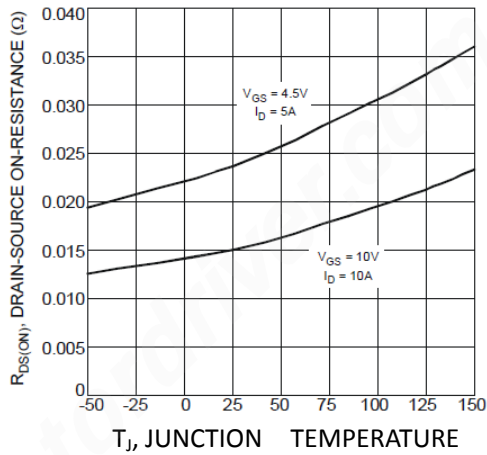


Figure7.On-Resistance Variation with Temperature

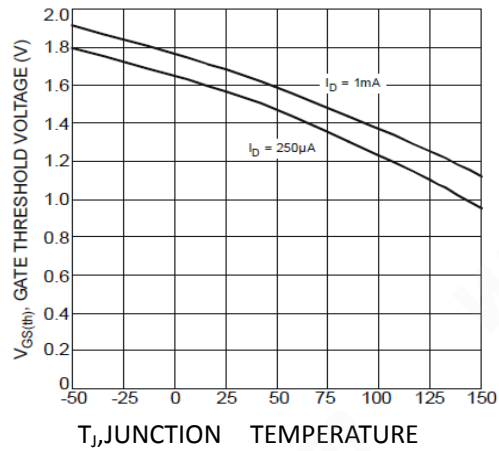


Figure8. Gate Threshold vs. Ambient Temperature

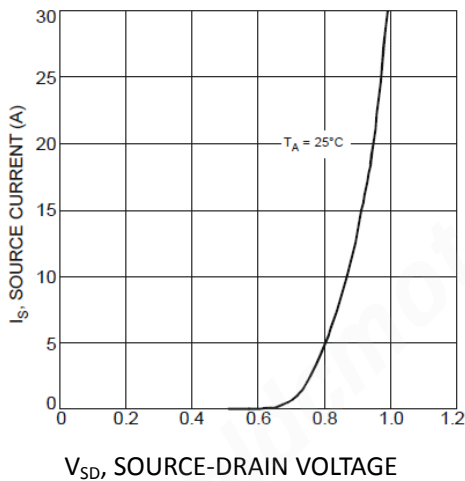


Figure9.Diode Forward Voltage vs. Current

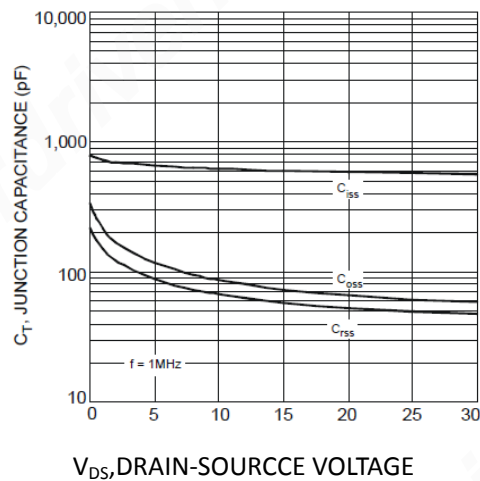


Figure10. Typical Junction Capacitance

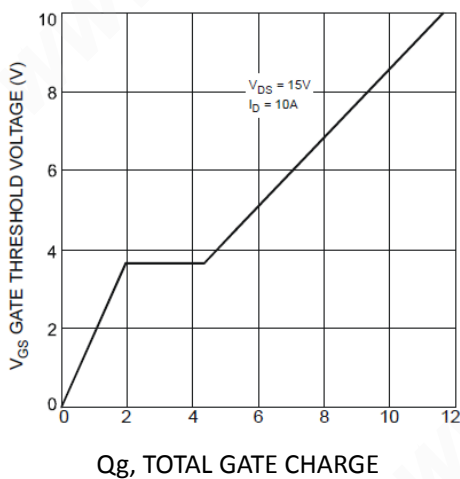


Figure11. Gate Charge

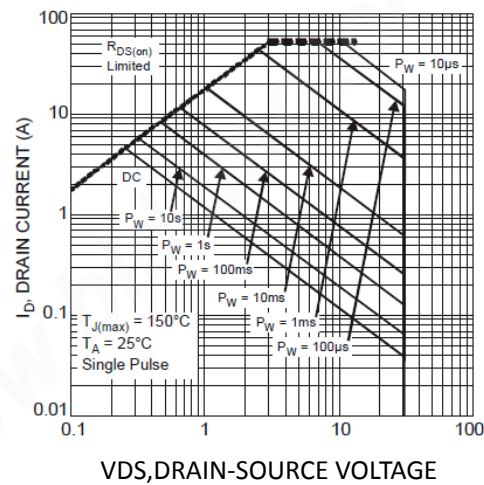


Figure12. SOA, Safe Operation Area

Typical Characteristics($T_J=25^{\circ}\text{C}$ Noted)

P-Channel

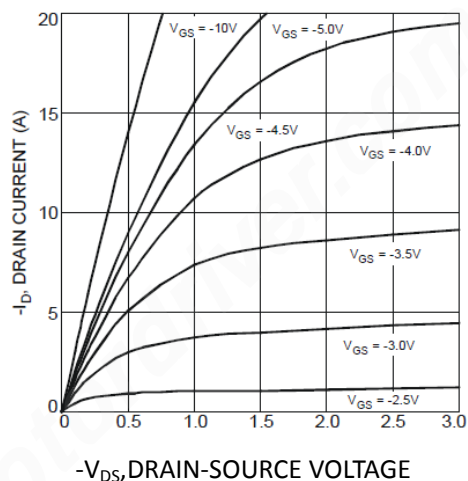


Figure13. Typical Output Characteristics

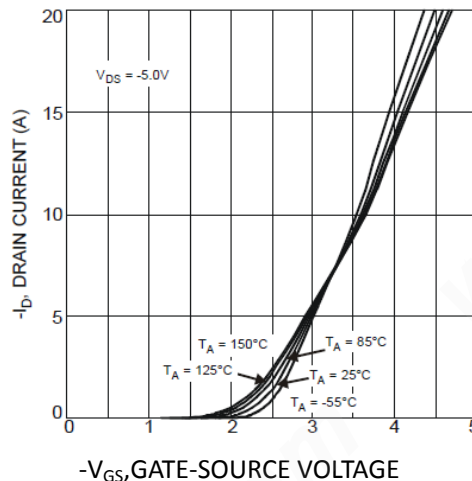


Figure14. Typical Transfer Characteristics

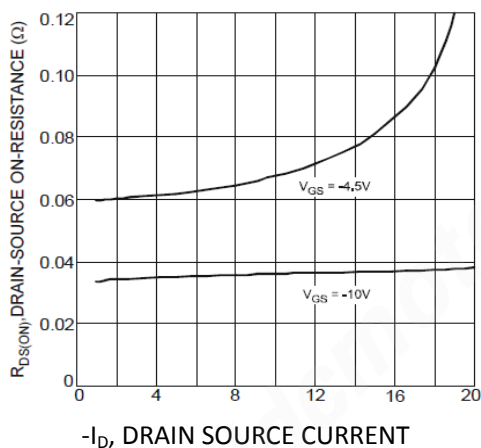


Figure15. Typical On-Resistance vs. Drain Current and Gate Voltage

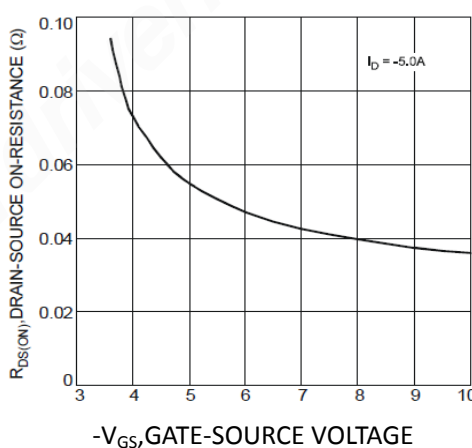


Figure16. Typical On-Resistance vs. Drain Current and Gate Voltage

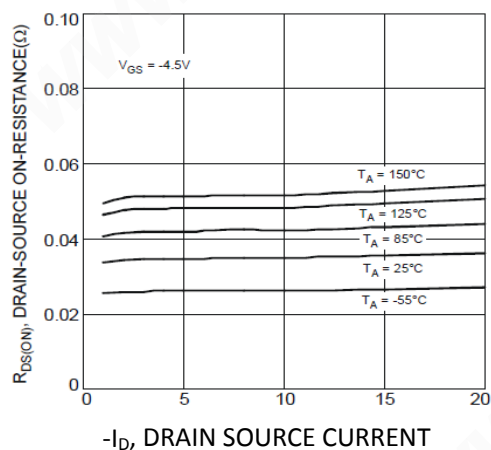


Figure17. Typical On-Resistance vs. Drain Current and Temperature

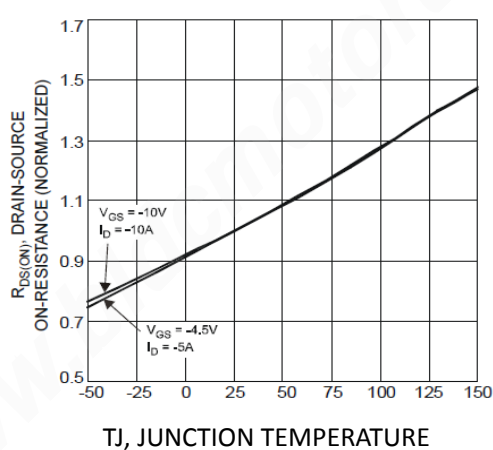


Figure18. On-Resistance Variation with Temperature

Typical Characteristics($T_J=25^{\circ}\text{C}$ Noted)

P-Channel

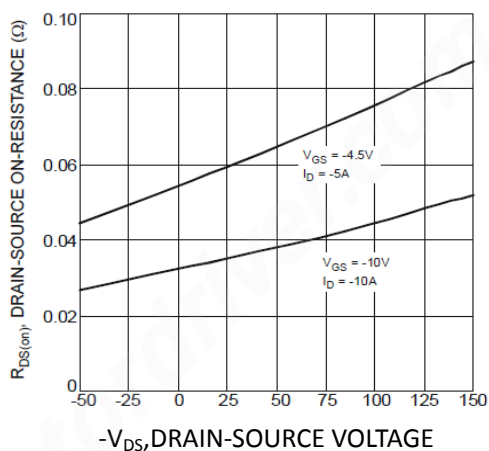


Figure19. On-Resistance Variation with Temperature

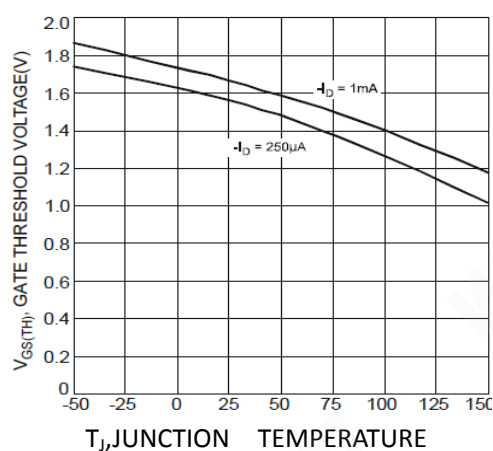


Figure20. Gate Threshold vs. Ambient Temperature

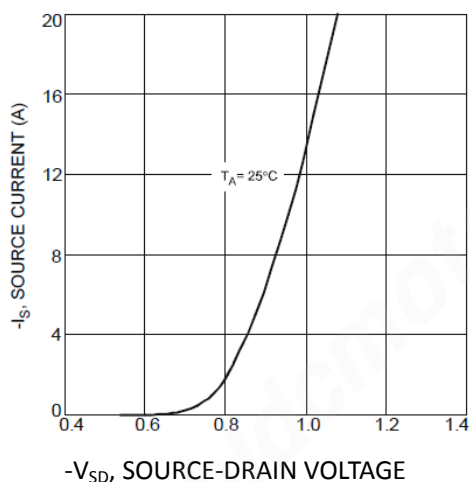


Figure21. Diode Forward Voltage vs. Current

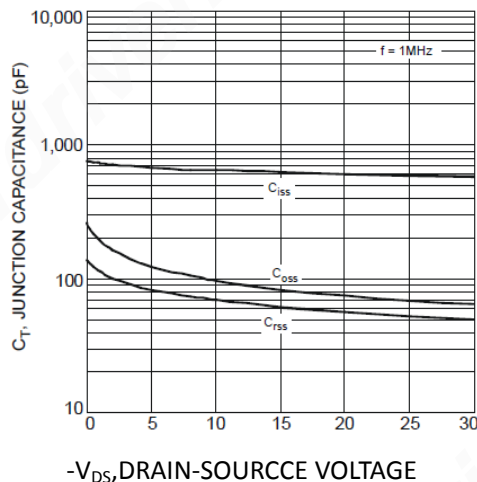


Figure22. Typical Junction Capacitance

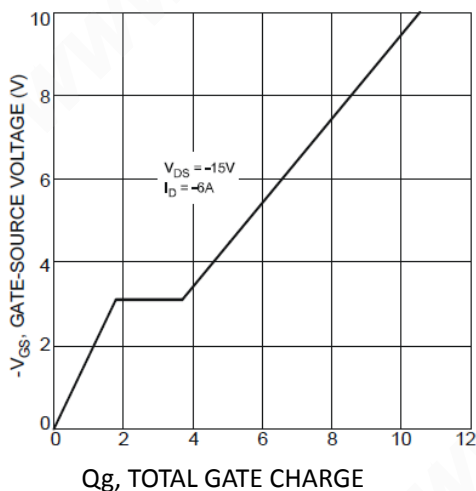


Figure23. Gate Charge

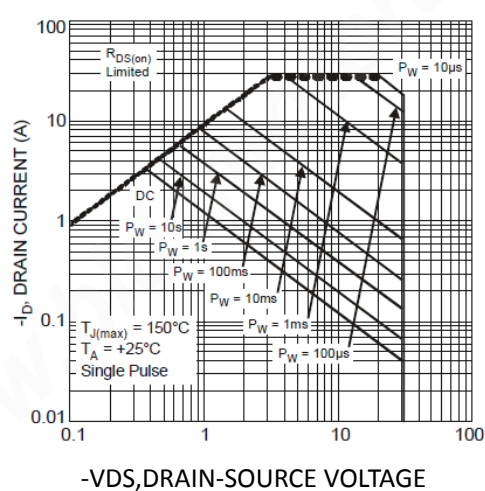
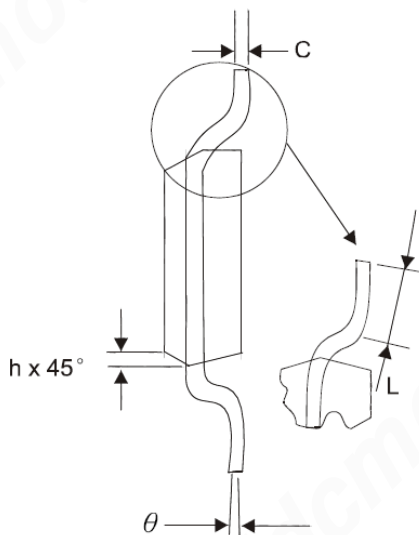
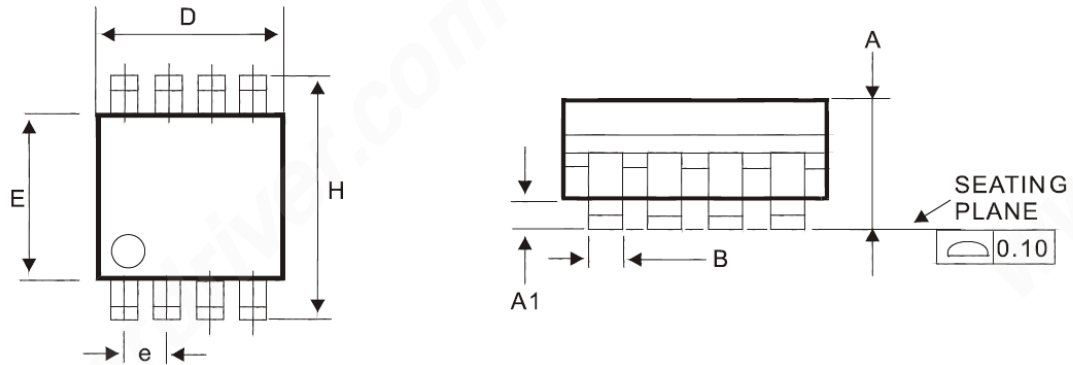


Figure24. SOA, Safe Operation Area

SOP-8 Package Outline



DIM	MILLIMETERS	
	MIN	MAX
A	1.35	1.75
A1	0.10	0.25
B	0.35	0.49
C	0.18	0.25
D	4.80	5.00
E	3.80	4.00
e	1.27 BSC	
H	5.80	6.20
h	0.25	0.50
L	0.40	1.25
θ	0°	7°